S/N 09/253,611

IN THE UNITED STATES AT TENT AND TRADEMARK OFFICE

Applicant:

Paul A. Farrar

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Title:

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Examiner: Ron Pompey Group Art Unit: 2812 Docket: 303.572US1

SELECTIVE DEPOSITION OF BALL CONTACTS

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on <u>March 28, 2001</u>. Please amend the above-identified patent application as follows.

IN THE DRAWINGS

Enclosed is a copy of Figure 6 of the drawings showing the following proposed amendment to Figure 6 in red ink. Reference numerals 210 and 215 are added to Figure 6. Support for these amendments to the drawings can be found on page 11, lines 24-28 of Applicant's disclosure and Figure 5, thus no new matter is introduced.

IN THE CLAIMS

Please add new claims 68-75 as follows:

68.(New)

The method recited in claim 1 performed in the order recited.

69.(New)

The method recited in claim13 performed in the order recited.

70.(New) The method recited in claim 13 wherein electrolytically depositing solder on the exposed portion of the metal contact pad, includes forming a solder contact extending below the resist layer and below a surface of the insulating layer;

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